

DEVELOPING METHOD FOR SEMICONDUCTOR SUBSTRATE

ABSTRACT OF THE DISCLOSURE

Embodiments of the present invention provide a developing method, which can efficiently prevent the developing solution from remaining on the backside surface of the wafer, so as to avoid the influence of the contamination on the subsequent processes. In one embodiment, a developing method comprises providing a wafer in a reaction space, wherein the wafer has an exposed photoresist thereon; coating a developing solution on a surface of the wafer; rotating the wafer; rinsing a normal surface and a backside surface of the wafer; and stopping rinsing the normal surface of the wafer while keeping rinsing the backside surface of the wafer for a specific time period.

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